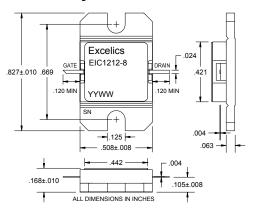


UPDATED 01/04/2006

12.20-12.70 GHz 8-Watt Internally Matched Power FET

FEATURES

- 12.20- 12.70GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +39.0 dBm Output Power at 1dB Compression
- 6.5 dB Power Gain at 1dB Compression
- 27% Power Added Efficiency
- -46 dBc IM3 at PO = 28.5 dBm SCL
- Hermetic Metal Flange Package
- 100% Tested for DC, RF, and R_{TH}



ELECTRICAL CHARACTERISTICS ($T_a = 25^{\circ}C$)

Caution! ESD sensitive device.

EIC1212-8

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SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	ТҮР	MAX	UNITS
P_{1dB}	Output Power at 1dB Compression $f = 12.20-12.70$ GHz $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200$ mA	38.5	39.0		dBm
G _{1dB}	Gain at 1dB Compressionf = 12.20-12.70GHz V_{DS} = 10 V, $I_{DSQ} \approx 2200$ mA	5.5	6.5		dB
∆G	$ Gain \ Flatness \qquad \qquad f = 12.20-12.70 \ GHz \\ V_{DS} = 10 \ V, \ I_{DSQ} \approx 2200 \ mA $			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200 \text{mA}$ f = 12.20-12.70GHz		27		%
Id _{1dB}	Drain Current at 1dB Compression f = 12.20-12.70GHz		2300	2600	mA
IM3	Output 3rd Order Intermodulation Distortion $\Delta f = 10 \text{ MHz}$ 2-Tone Test; Pout = 28.5 dBm S.C.L ² $V_{DS} = 10 \text{ V}$, $I_{DSQ} \approx 65\%$ IDSS $f = 12.70 \text{GHz}$	-43	-46		dBc
I _{DSS}	Saturated Drain Current V_{DS} = 3 V, V_{GS} = 0 V		4000	5000	mA
V _P	Pinch-off Voltage V _{DS} = 3 V, I _{DS} = 40 mA		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		3.5	4.0	°C/W
Note: 1) T	ested with 100 Obm gate resistor 2) S C L = Single Carrier Level	2) Overal	Rth depends		t'a a

Note: 1) Tested with 100 Ohm gate resistor. 2) S.C.L. = Single Carrier Level.

3) Overall Rth depends on case mounting

ABSOLUTE MAXIMUM RATING^{1,2}

SYMBOL	CHARACTERISTIC	VALUE
V _{DS}	Drain to Source Voltage	10 V
V _{GS}	Gate to Source Voltage	-4.5 V
I _{DS}	Drain Current	IDSS
I _{GSF}	Forward Gate Current	80 mA
P _{IN}	Input Power	@ 3dB compression
PT	Total Power Dissipation	38 W
T _{CH}	Channel Temperature	175°C
T _{STG}	Storage Temperature	-65/+175°C

Notes: 1.

Operating the device beyond any of the above ratings may result in permanent damage or reduction of MTTF.

2. Bias conditions must also satisfy the following equation $P_T < (T_{CH} - T_{PKG})/R_{TH}$, where \overline{T}_{PKG} = temperature of package, and $P_T = (V_{DS} * I_{DS}) - (P_{OUT} - P_{IN})$.

Specifications are subject to change without notice. Excelics Semiconductor, Inc. 310 De Guigne Drive, Sunnyvale, CA 94085 Phone: 408-737-1711 Fax: 408-737-1868 Web: <u>www.excelics.com</u>